

TOPWAY LMT050FNCFWA LCD Module Smart Displays



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TOPWAY

TOPWAY LMT050FNCFWA LCD Module Smart Displays



Specifications

- Screen Size(Diagonal) : 5.0 inch
- Resolution : 800(RGB) x 480
- Signal Interface: MIPI
- Color Depth: 16.7M color (24bit)
- Pixel Pitch : 0.135 x 0.135 (mm)
- Pixel Configuration: RGB Stripe
- Display Mode: Transmissive/normal Black
- Surface Treatment: Clear HC(3H)
- Viewing Direction: Full
- Outline Dimension: 136.00×78.81×7.0 (mm) (exclude FPC, see attached drawing for details)
- Active Area : 108 x 64.8 (mm)
- Backlight: 9 LEDs
- Storage Temperature : Note: *1. Color tone may slightly change by Temperature and Driving Conditions.

Product Usage Instructions

1. Power On/Off Sequence

Follow the specified power on/off sequence provided in the user manual to ensure proper functionality and longevity of the LCD module.

2. Interface Connection

Connect the MIPI signal interface properly to ensure correct communication between the display module and the connected device.

3. Handling and Care

Handle the LCD module with care to avoid any damage to the display screen or internal components. Use a soft, lint-free cloth for cleaning the screen.

4. Backlight Adjustment

If needed, adjust the backlight settings according to your preference or ambient lighting conditions for optimal viewing experience.

Frequently Asked Questions

- **Q: Can the resolution be adjusted on the LCD module?**
 - A: The resolution of the LCD module is fixed at 800(RGB) x 480 and cannot be adjusted.
- **Q: How many LEDs are used in the backlight of the LCD module?**
 - A: The LCD module uses 9 LEDs in its backlight circuit for illumination.

Prepared by: Chen Zhonghua	Checked by:	Approved by:
Date: 2024-04-24	Date:	Date:

Rev.	Descriptions	Edit	Release Date
0.1	Preliminary	Chen Zhonghua	2024-04-24

General Specification

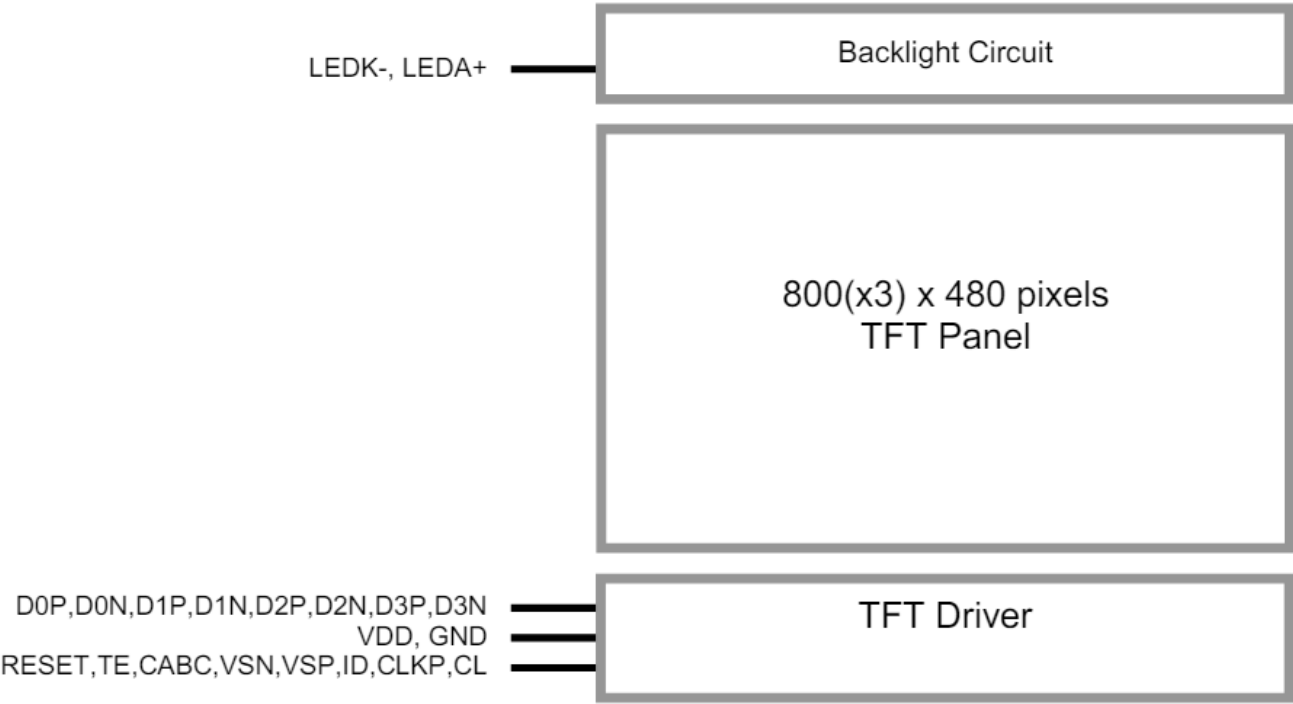
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- Viewing Direction: Full
- Outline Dimension: 136.00×78.81×7.0 (mm) (exclude FPC, see attached drawing for details)

- Active Area : 108 x 64.8 (mm)
- Backlight: 9 LEDs
- Operating Temperature: -20 ~ +70°C
- Storage Temperature: -30 ~ +80°C

Note:

*1. Color tone may slightly change by Temperature and Driving Conditions.

Block Diagram



Terminal Functions

Interface

Match connector type CN1: 62684-3211D0ALF

Pin No.	Pin Name	I/O	Descriptions
1	GND	P	Power Ground (0V)
2	GND	P	Power Ground (0V)
3	ID(GND)	O	ID
4	LEDK	P	Backlight LED Cathode supply
5	LEDA	p	Backlight LED Anode supply
6	NC	—	No connection

7	D0N	I	MIPI D0-
8	D0P	I	MIPI D0+
9	GND	P	Power Ground (0V)
10	D1N	I	MIPI D1-
11	D1P	I	MIPI D1+
12	GND	p	Power Ground (0V)
13	CLKN	I	MIPI CLK-
14	CLKP	I	MIPI CLK+
15	GND	P	Power Ground (0V)
16	D2N	I	MIPI D2-
17	D2P	I	MIPI D2+
18	GND	P	Power Ground (0V)
19	D3N	I	MIPI D3-
20	D3P	I	MIPI D3+
21	GND	P	Power Ground (0V)
22	IOVCC	P	Power supply(3.3v)
23	IOVCC	P	Power supply(3.3v)
24	GND	P	Power Ground (0V)
25	VSP	P	Positive Source Power
26	VSN	P	Negative Source Power
27	GND	P	Power Ground (0V)
28	CABC	O	backlight control
29	TE	O	Serves TE (Tearing Effect) pin
30	RESET	I	LCD Reset pin
31	GND	P	Power Ground (0V)
32	GND	P	Power Ground (0V)

Note: I/O Definition

I—Input, O—Output, P—Power/Ground

Absolute Maximum Ratings

GND=0V, Ta = 25°C

Items	Symbol	Min.	Max.	Unit	Condition
Supply Voltage	IOVCC	-0.3	+5.5	V	GND = 0V
Supply Voltage	VSP	-0.3	+6.6	V	
Supply Voltage	VSN	0.3	-6.6	V	
Logic Input voltage range	VIN	-0.3	IOVCC+0.3	V	
Logic Output voltage range	VO	-0.3	IOVCC+0.3	V	
Differential Input voltage	HSSI_CLK_P/N, HSSI_DATA0_P/N, HSSI_DATA1_P/N HSSI_DATA2_P/N HSSI_DATA3_P/N	-0.3	1.8	V	
Operating Temperature	TOP	-20	+70	°C	No Condensation
Storage Temperature	TST	-30	+80	°C	No Condensation

Cautions:

Any Stresses exceeding the Absolute Maximum Ratings may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

Electrical Characteristics

DC Characteristics

IOVCC =3.3V, GND=0V, Ta =25°C

Items	Symbol	MIN.	TYP.	MAX.	Unit	Applicable Pin
Operating Voltage	IOVCC	3.2	3.3	3.4	V	
Operating Voltage	VSP	5.4	5.5	5.6	V	
Operating Voltage	VSN	-5.6	-5.5	-5.4	V	
Input High Voltage	VIH	0.7 IOVCC	–	IOVCC	V	
Input Low Voltage	VIL	GND	–	0.3VDD	V	
Output Signal Low Voltage	VoH	0.8 IOVCC	–	IOVCC	V	
Output Signal High Voltage	VOL	GND	–	0.2 IOVCC	V	
Operating Current (*1)	I_IOVCC	–	25	–	mA	white pattern

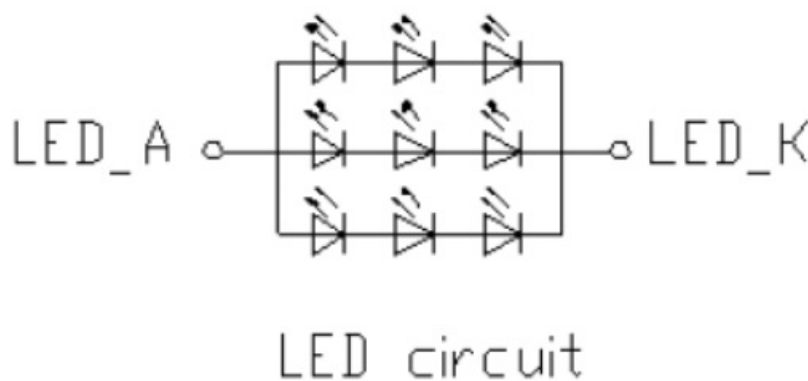
LED Backlight Circuit Characteristic

IVLED=60mA, Ta=25°C

Items	Symbol	MIN.	TYP.	MAX.	Unit	Note
Forward Voltage	VLED	8.1	9.0	9.9	V	
Forward Current	IVLED	–	60	–	mA	
Life Time	–	20,000	–	–	hrs	

Cautions:

Exceeding the recommended driving current could cause substantial damage to the backlight and shorten its lifetime



MIPI DC Characteristics

DC Characteristics for DSI LP Mode

Parameter	Symbol	Conditions	Specification			UNIT
			MIN	TYP	MAX	
Logic high level input voltage	V_{IHLPCD}	LP-CD	450	-	1350	mV
Logic low level input voltage	V_{ILLPCD}	LP-CD	0	-	200	mV
Logic high level input voltage	V_{IHLPRX}	LP-RX (CLK, D0)	880	-	1350	mV
Logic low level input voltage	V_{ILLPRX}	LP-RX (CLK, D0)	0	-	550	mV
Logic low level input voltage	$V_{ILLPRXULP}$	LP-RX (CLK ULP mode)	0	-	300	mV
Logic high level output voltage	V_{OHLPTX}	LP-TX (D0)	1.1	-	1.3	V
Logic low level output voltage	V_{OLLPTX}	LP-TX (D0)	-50	-	50	mV
Logic high level input current	I_{IH}	LP-RX, $V_{in}=0\sim 1.3V$	-	-	10	μA
Logic low level input current	I_{IL}	LP-RX, $V_{in}=0\sim 1.3V$	-10	-	-	μA
Input pulse rejection	SGD	DSI-CLK+/-, DSI-Dn+/- (Note 3)	-	-	300	Vps

Note 1) $V_{DDI}=1.65\sim 3.6V$, $DVSS=VSSAM=AVSS=VSSB=VSSR=0V$, $T_a=-30$ to $70\text{ }^{\circ}C$ (to $+85\text{ }^{\circ}C$ no damage).

Note 2) DSI high speed is off.

Note 3) Peak interference amplitude max. 200mV and interference frequency min. 450MHz.

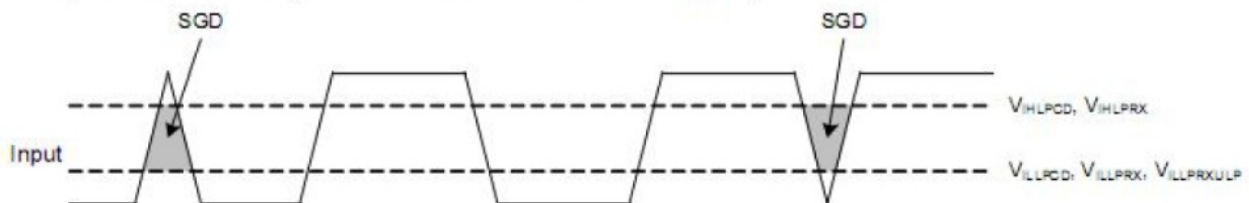


Fig. 7.2.2 Spike/Glitch rejection-DSI

DC Characteristics for DSI HS Mode

Parameter	Symbol	Condition	Specification			Unit
Input Common Mode Voltage for Clock	V_{CMCLK}	CLKP/N Note 2, Note 3	70	-	330	mV
Input Common Mode Voltage for Data	V_{CMDATA}	DnP/N Note 2, Note 3, Note 5	70	-	330	mV
Common Mode Ripple for Clock Equal or Less than 450MHz	$V_{CMRCLK450}$	CLKP/N Note 4	-50	-	50	mV
Common Mode Ripple for Data Equal or Less than 450MHz	$V_{CMRDATAL450}$	DnP/N Note 4, Note 5	-50	-	50	mV
Common Mode Ripple for Clock More than 450MHz (peak sine wave)	$V_{CMRCLKM450}$	CLKP/N	-	-	100	mV
Common Mode Ripple for Data More than 450MHz (peak sine wave)	$V_{CMRDATAM450}$	DnP/N Note 5	-	-	100	mV
Differential Input Low Level Threshold Voltage for Clock	V_{THCLK-}	CLKP/N	-70	-	-	mV
Differential Input Low Level Threshold Voltage for Data	$V_{THDATA-}$	DnP/N Note 5	-70	-	-	mV
Differential Input High Level Threshold Voltage for Clock	V_{THCLK+}	CLKP/N	-	-	70	mV
Differential Input High Level Threshold Voltage for Data	$V_{THDATA+}$	DnP/N Note 5	-	-	70	mV
Single-ended Input Low Voltage	V_{LHS}	CLKP/N, DnP/N Note 3, Note 5	-40	-	-	mV
Single-ended Input High Voltage	V_{IHHS}	CLKP/N, DnP/N Note 3, Note 5	-	-	460	mV
Differential Termination Resistor	R_{TERM}	CLKP/N, DnP/N Note 5	80	100	125	Ω
Single-ended Threshold Voltage for Termination Enable	$V_{TERM-EN}$	CLKP/N, DnP/N Note 5	-	-	450	mV
Termination Capacitor	C_{TERM}	CLKP/N, DnP/N Note 5, Note 6	-	-	60	pF

Notes:

1. $T_a = -30^{\circ}\text{C}$ to 70°C (to $+85^{\circ}\text{C}$ no damage), $V_{CI} = 2.5\text{V}$ to 6.6V , $V_{DDI} = 1.65\text{V}$ to 3.6V
2. Includes 50mV (-50mV to 50mV) ground difference
3. Without $V_{CMRCLKM450}/V_{CMRDATAM450}$
4. Without 50mV (-50mV to 50mV) ground difference
5. $n = 0$ and 1
6. For higher bit rates, a 14pF capacitor will be needed to meet the common-mode return loss specification.

AC Characteristics

MIPI DSI Timing Characteristics

High-Speed Mode

(DVSS=VSSAM=AVSS=VSSB=VSSR=0V, VDDI=1.65V to 3.6V, Ta = -30 to 70°C)

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
DSI-CLK+/-	$2 \times U_{INST}$	Double UI instantaneous	3.32	-	5	ns	4 Lane (Note 2)
DSI-CLK+/-	U_{INSTA} U_{INSTB}	UI instantaneous half ($UI = U_{INSTA} = U_{INSTB}$)	1.66	-	2.5	ns	4 Lane (Note 2)
DSI-Dn+/-	t_{DS}	Data to clock setup time	$0.15 \times UI$	-	-	ps	
DSI-Dn+/-	t_{DH}	Data to clock hold time	$0.15 \times UI$	-	-	ps	
DSI-CLK+/-	t_{DRTCLK}	Differential rise time for clock	150	-	$0.3 \times UI$	ps	
DSI-Dn+/-	$t_{DRTDATA}$	Differential rise time for data	150	-	$0.3 \times UI$	ps	
DSI-CLK+/-	t_{DFTCLK}	Differential fall time for clock	150	-	$0.3 \times UI$	ps	
DSI-Dn+/-	$t_{DFTDATA}$	Differential fall time for data	150	-	$0.3 \times UI$	ps	

Note 1) Dn = D0, D1, D2 and D3.

Note 2) Maximum total bit rate is 2.4Gbps for 24-bit data format, 1.8Gbps for 18-bit data format and 1.6Gbps for 16-bit data format in 3 lanes or 4 lanes application which support to 800RGBx 1280 resolution.

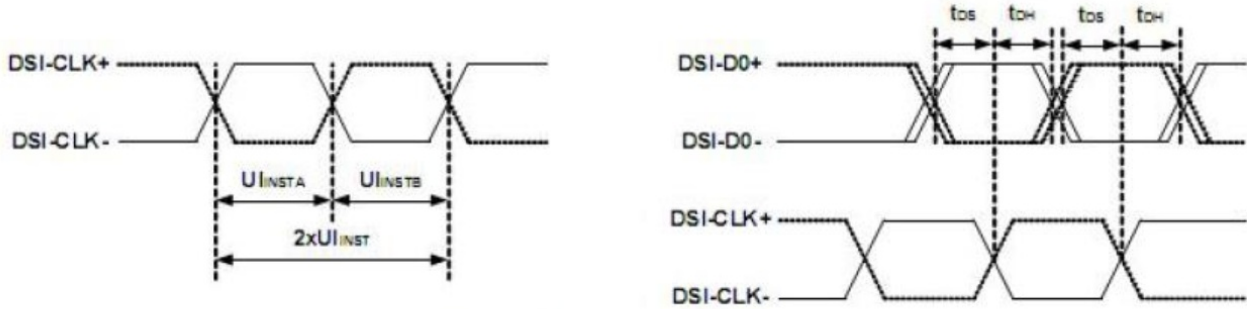


Fig. 7.3.1 DSI clock channel timing

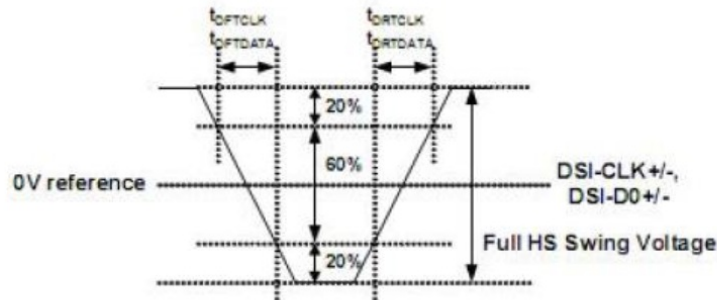


Fig. 7.3.2 Rising and fall time on clock and data channel

Low Power Mode

(DVSS=VSSAM=AVSS=VSSB=VSSR=0V, VDDI=1.65V to 3.6V, Ta = -30 to 70°C)

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
DSI-D0+/-	T_{LPXM}	Length of LP-00, LP-01, LP-10 or LP-11 periods MPU → Display Module	50	-	75	ns	Input
DSI-D0+/-	T_{LPXD}	Length of LP-00, LP-01, LP-10 or LP-11 periods Display Module → MPU	50	-	75	ns	Output
DSI-D0+/-	$T_{TA-SURED}$	Time-out before the MPU start driving	T_{LPXD}	-	$2 \times T_{LPXD}$	ns	Output
DSI-D0+/-	$T_{TA-GETD}$	Time to drive LP-00 by display module	-	$5 \times T_{LPXD}$	-	ns	Input
DSI-D0+/-	T_{TA-GOD}	Time to drive LP-00 after turnaround request - MPU	-	$4 \times T_{LPXD}$	-	ns	Output

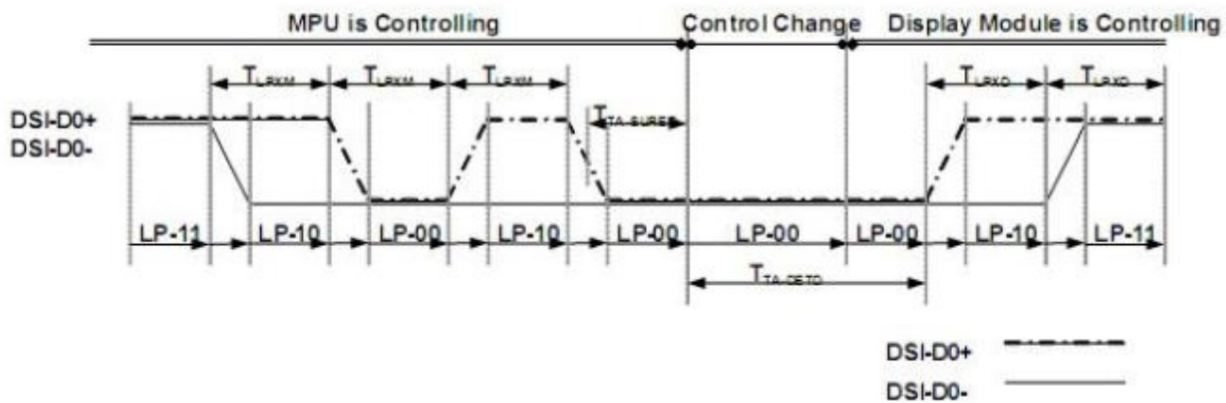


Fig. 7.3.3 Bus Turnaround (BTA) from MPU to display module Timing

Fig. 7.3.3 Bus Turnaround (BTA) from MPU to display module Timing

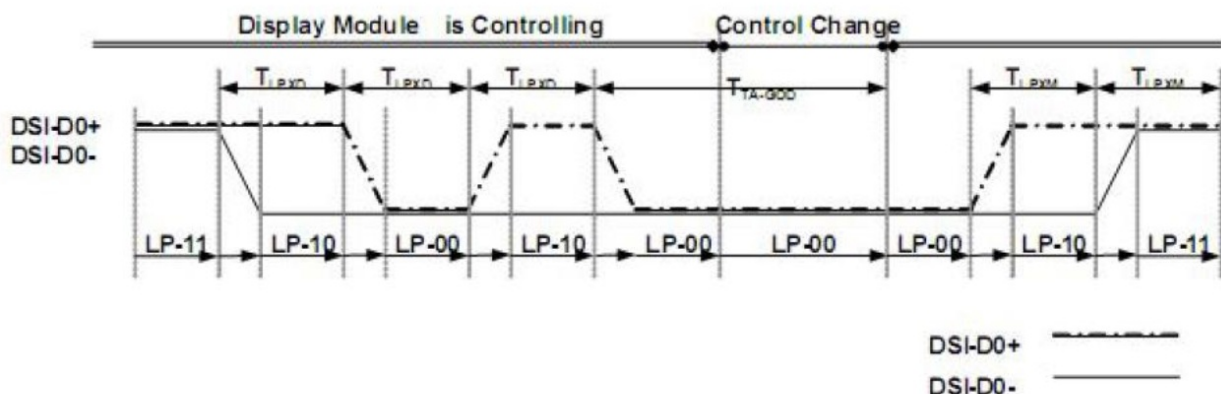


Fig. 7.3.4 Bus Turnaround (BTA) from display module to MPU Timing

DSI Bursts

(DVSS=VSSAM=AVSS=VSSB=VSSR=0V, VDDI=1.65V to 3.6V, $T_a = -30$ to 70°C)

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
Low Power Mode to High Speed Mode Timing							
DSI-Dn+/-	T_{LPX}	Length of any low power state period	50	-	-	ns	Input
DSI-Dn+/-	$T_{HS-PREPARE}$	Time to drive LP-00 to prepare for HS transmission	$40+4xUI$	-	$85+6xUI$	ns	Input
DSI-Dn+/-	$T_{HS-TERM-EN}$	Time to enable data receiver line termination measured from when Dn crosses V_{ILMAX}	-	-	$35+4xUI$	ns	Input
High Speed Mode to Low Power Mode Timing							
DSI-Dn+/-	$T_{HS-SKIP}$	Time-out at display module to ignore transition period of EoT	40	-	$55+4xUI$	ns	Input
DSI-Dn+/-	$T_{HS-EXIT}$	Time to drive LP-11 after HS burst	100	-	-	ns	Input
DSI-Dn+/-	$T_{HS-TRAIL}$	Time to drive flipped differential state after last payload data bit of a HS transmission burst	$60+4xUI$	-	-	ns	Input

High Speed Mode to/from Low Power Mode Timing

DSI-CLK+/-	TCLK-POS	Time that the MPU shall continue sending HS clock after the last associated data lane has transition to LP mode	60+52xUI	-	-	ns	Input
DSI-CLK+/-	TCLK-TRAIL	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	-	ns	Input
DSI-CLK+/-	THS-EXIT	Time to drive LP-11 after HS burst	100	-	-	ns	Input
DSI-CLK+/-	TCLK-PREPARE	Time to drive LP-00 to prepare for HS transmission	38	-	95	ns	Input
DSI-CLK+/-	TCLK-TERM-EN	Time-out at clock lane display module to enable HS transmission	-	-	38	ns	Input
DSI-CLK+/-	TCLK-PREPARE + TCLK-ZERO	Minimum lead HS-0 drive period before starting clock	300	-	-	ns	Input
DSI-CLK+/-	TCLK-PRE	Time that the HS clock shall be driven prior to any associated data lane beginning the transition from LP to HS mode	8xUI	-	-	ns	Input

Note 1) $D_n = D_0, D_1, D_2$ and D_3 .

Note 2) Two HS transmission can be sent with a break as short as $T_{HS-EXIT}$ from each other in continuous clock mode. In discontinuous mode, the break is longer which account $T_{CLK-POS}$, $T_{CLK-TRAIL}$ and $T_{HS-EXIT}$, before activity in clock and data lanes again.

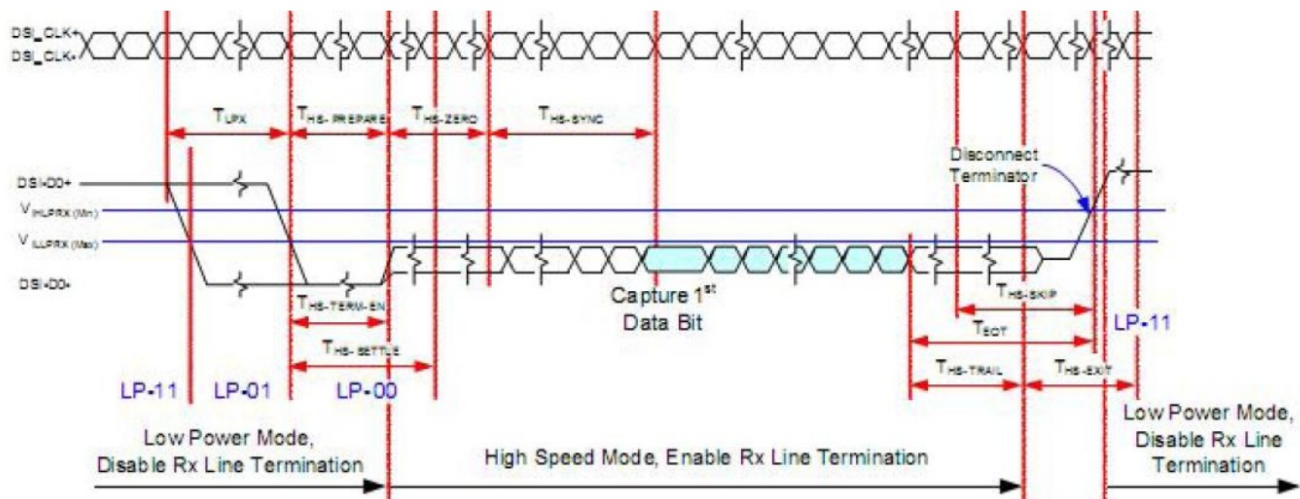


Fig. 7.3.5 Data lanes-Low Power Mode to/from High Speed Mode Timing

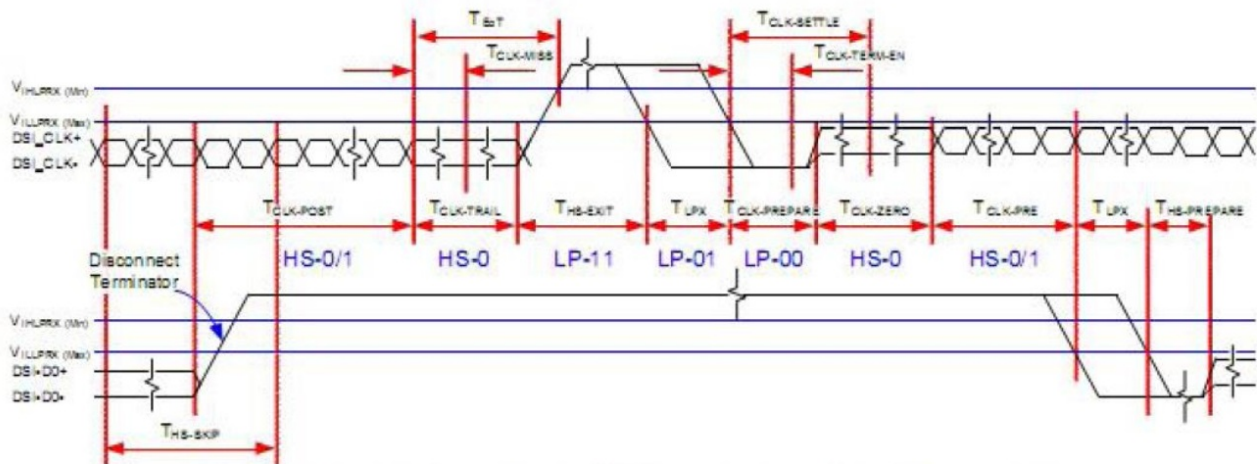


Fig. 7.3.6 Clock lanes- High Speed Mode to/from Low Power Mode Timing

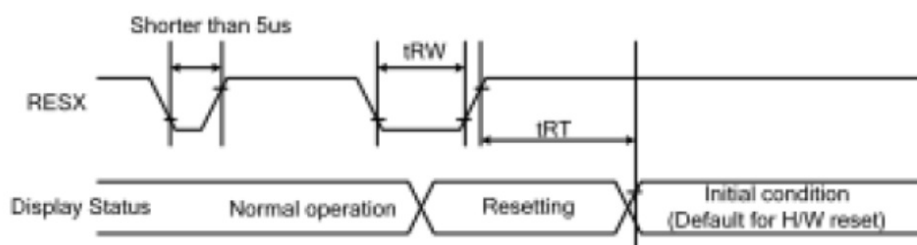


Figure 124: Reset Timing

Table 47: Reset Timing

Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		μs
	tRT	Reset cancel		5 (note 1,5) 120 (note 1,6,7)	mS

Notes:

1. The reset cancel also includes required time for loading ID bytes, VCOM setting and other settings from EEPROM to registers. This loading is done every time when there is H/W reset cancel time (tRT) within 5 ms after a rising edge of RESX.
2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the Table 48.

Table 48: Reset Descript

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

3. During the Resetting period, the display will be blanked (The display enters the blanking sequence, which maximum time is 120 ms, when Reset Starts in the Sleep Out mode. The display remains the blank state in the Sleep In mode.) and then return to Default condition for Hardware Reset.
4. Spike Rejection can also be applied during a valid reset pulse, as shown below:

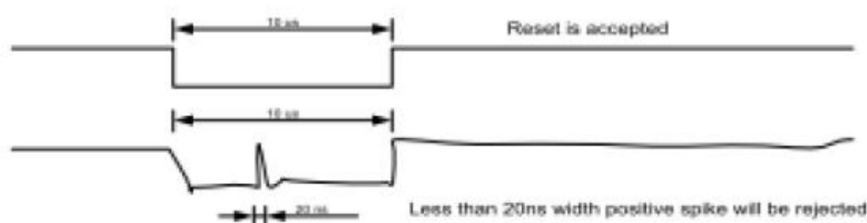


Figure 125: Positive Noise Pulse during Reset Low

5. When Reset applied during Sleep In Mode.
6. When Reset applied during Sleep Out Mode.
7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

Deep Standby Mode Timing

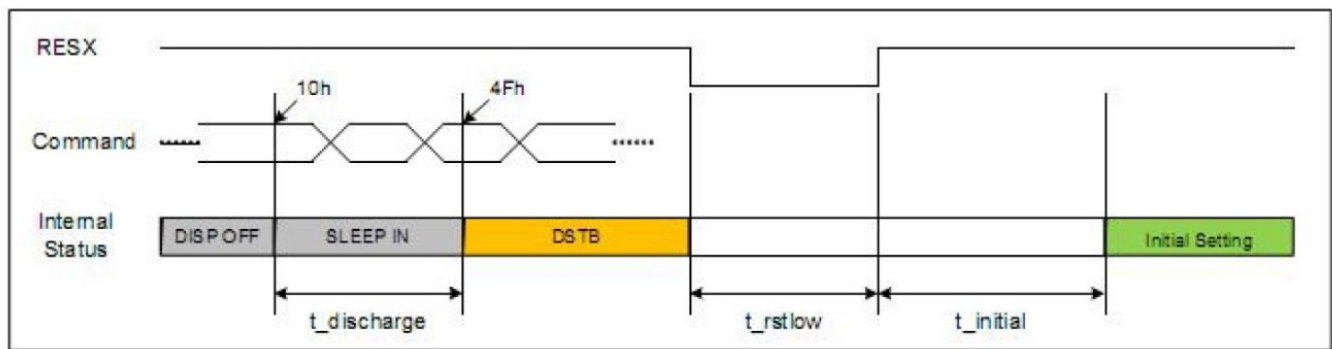


Fig. 7.3.8 Deep standby timing

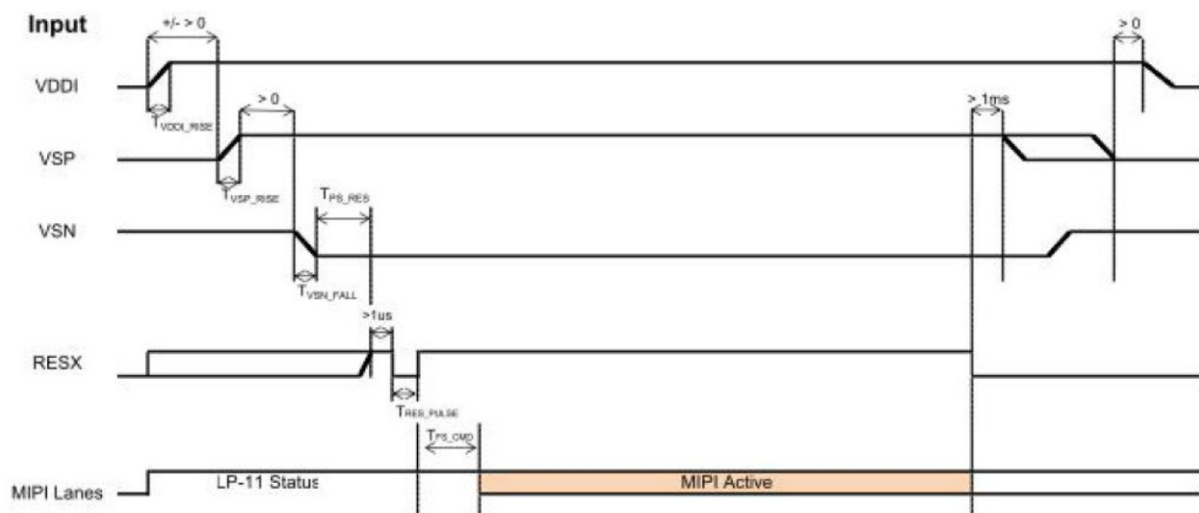
(DVSS=VSSAM=AVSS=VSSB=VSSR=0V, VDDI=1.65V to 3.6V, Ta = -30 to 70°C)

Signal	Symbol	Parameter	MIN	TYP	MAX	Unit	Description
RESX	$t_{\text{discharge}}$	Sleep in into DSTB delay time	100	-	-	ms	
	t_{rstlow}	Reset low pulse	3	-	-	ms	
	t_{initial}	Reset high to initial setting delay time	120	-	-	ms	

Note 1) $t_{\text{discharge}}$ suggested delay time over 100ms.

Note 2) t_{initial} suggested delay time over 120ms..

Power On/Off Sequence



Symbol	Characteristics	Min.	Typ.	Max.	Units
$T_{\text{VDDI_RISE}}$	VDDI Rise time	10	-	-	us
$T_{\text{VSP_RISE}}$	VSP Rise time	130	-	-	us
$T_{\text{VSN_FALL}}$	VSN Fall time	200	-	-	us
$T_{\text{PS_RES}}$	VDDI/VSP on to Reset high	5	-	-	ms
$T_{\text{RES_PULSE}}$	Reset low pulse time	10	-	-	us
$T_{\text{FS_CMD}}$	Reset to first command	10	-	-	ms

Figure 104: Power on/off sequence with Power Mode 2A

Optical Characteristics

Item		Symbol	Condition	MIN.	TYP.	MAX.	UNIT	Note.
Viewing angle		θT	(CR≥10)	70	80	—	degree	Note 2
		θB		70	80	—		
		θL		70	80	—		
		θR		70	80	—		
Contrast ratio		CR	θ=0o	500	600	—	—	Note 1,3
Response Time		Ton	25°C	—	20	30	msec	Note 1,4
		Toff					msec	
Chromaticlty	White	X	Backlight is on	0.259	0.309	0.359		Note 1,5
		Y		0.271	0.321	0.371		
	Red	X		0.541	0.591	0.641		
		Y		0.302	0.352	0.402		
	Green	X		0.296	0.346	0.396		
		Y		0.529	0.579	0.629		
	Blue	X		0.101	0.151	0.201		
		Y		0.040	0.090	0.140		
Luminance		L		260	350	—	cd/m2	Note 1,6
NTSC				—	50		%	Note 5
Luminance uniformity		U		75	80	—	%	Note 1,7
Gamma				—	2.2	—		

Test Conditions:

1. I_VLED= 60mA, VLED=9.0V, and the ambient temperature is 25. °C
2. The test systems refer to Note 1 and Note 2.

Note 1:

The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment SR-3A (1°)

Measuring condition:

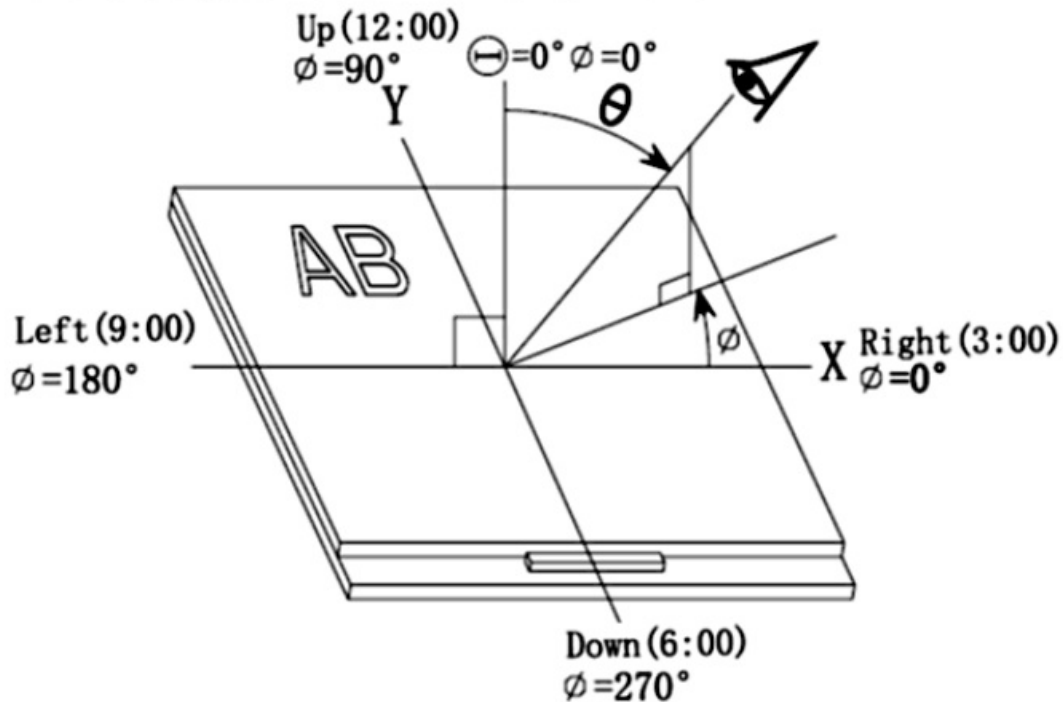
- Measuring surroundings: Darkroom
- Measuring temperature: Ta=25°C.
- Adjust the operating voltage to get optimum contrast at the center of the display

Note 2:

The definition of viewing angle:

Refer to the graph below marked by θ and ϕ

Refer to the graph below marked by θ and ϕ

**Note 3:**

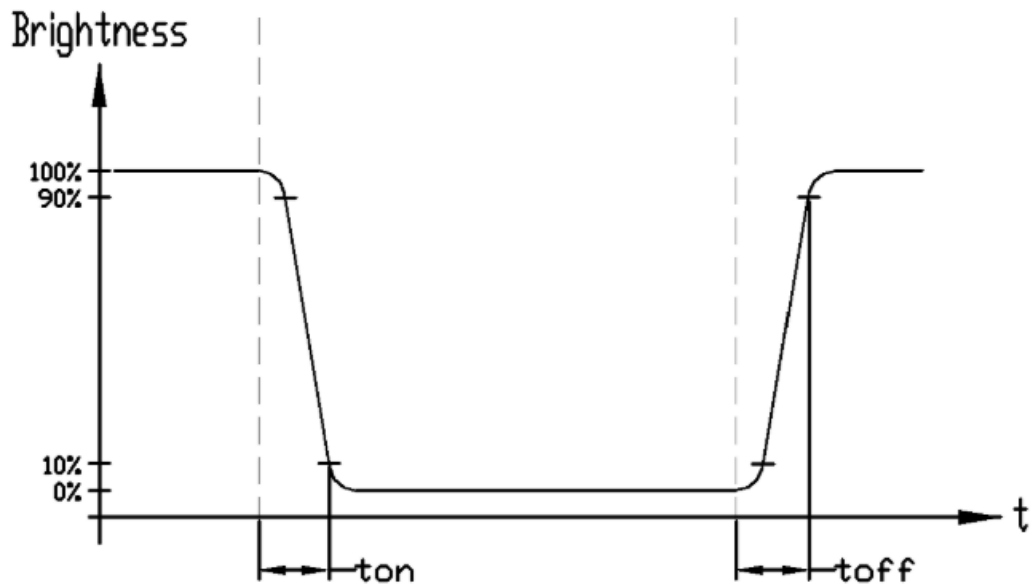
The definition of contrast ratio (Test LCM using SR-3A (1°)):

$$\text{Contrast Ratio (CR)} = \frac{\text{Luminance When LCD is at "White" state}}{\text{Luminance When LCD is at "Black" state}}$$

Note 4:

Definition of Response time. (Test LCD using BM-7A(2°)):

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of amplitudes. Refer to figure as below.

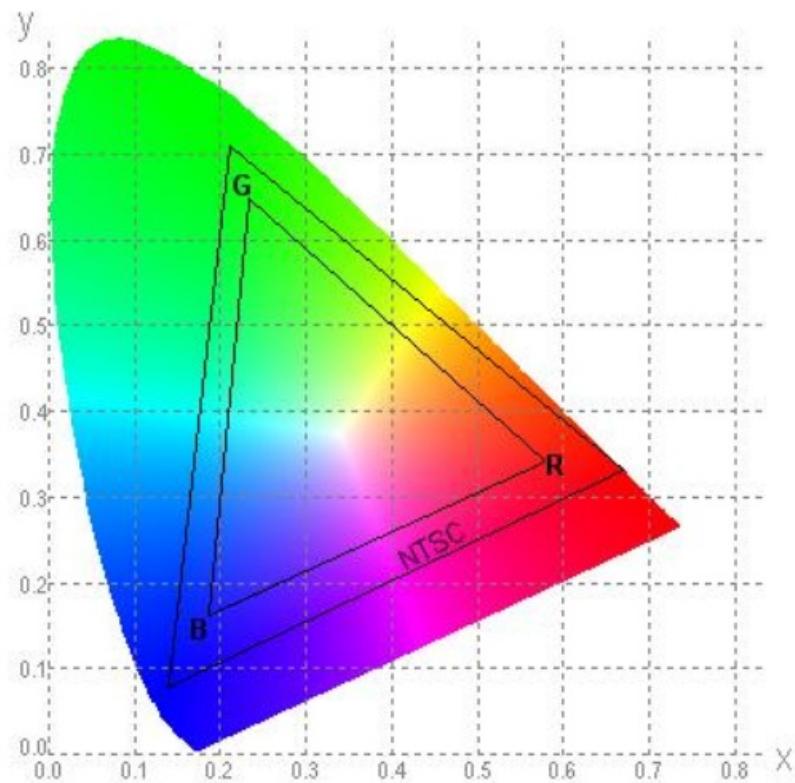


Note 5:

Definition of Color of CIE1931 Coordinate and NTSC Ratio

Color gamut:

$$S = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}} \times 100\%$$



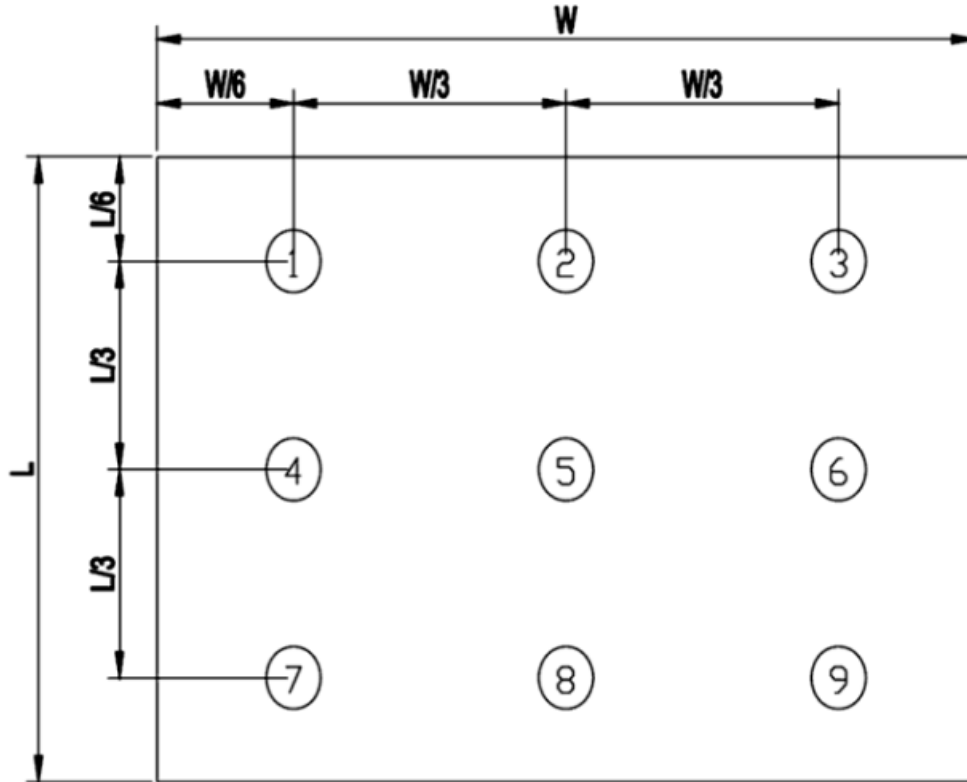
Note 6:

The luminance uniformity is calculated by using following formula.

$$\Delta B_p = B_p (\text{Min.}) / B_p (\text{Max.}) \times 100 (\%)$$

$B_p (\text{Max.})$ = Maximum brightness in 9 measured spots

$B_p (\text{Min.})$ = Minimum brightness in 9 measured spots.



Note 7:

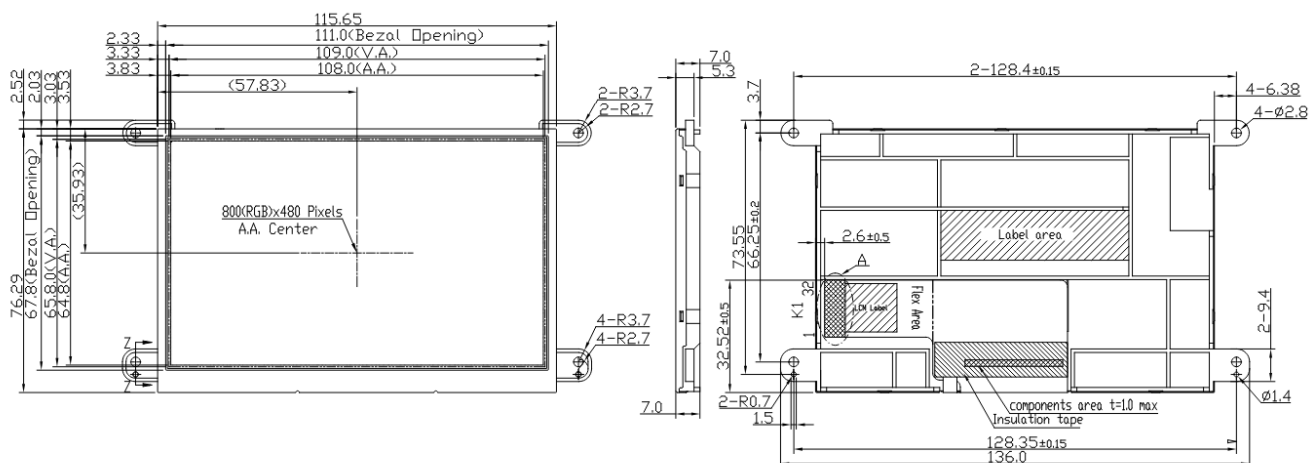
Measured the luminance of white state at center point

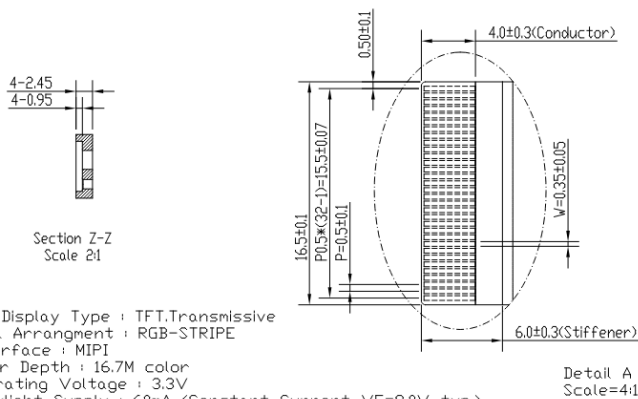
Warranty

LCD Module Design and Handling Precaution

- Please ensure V0, VCOM is adjustable, to enable LCD module get the best contrast ratio under different temperatures, view angles and positions.
- Normally display quality should be judged under the best contrast ratio within viewable area. Unexpected display pattern may come out under abnormal contrast ratio.
Never operate the LCD module exceed the absolute maximum ratings.
- Never apply signal to the LCD module without power supply. No Hot-plugging
- WARNING! Be aware of (if any) frame grounding of the LCD Module connection with the system which may cause safety issue (e.g. electric shock, etc).
- Keep signal line as short as possible to reduce external noise interference.
- IC chip (e.g. TAB or COG) is sensitive to light. Strong light might cause malfunction. Light sealing structure casing is recommended.
- Make sure there is enough space (with cushion) between case and LCD panel, to prevent external force passed on to the panel; otherwise that may cause damage to the LCD and degrade its display result.
- Avoid showing a display pattern on screen for a long time (continuous ON segment).
- LCD module reliability may be reduced by temperature shock.
- When storing and operating LCD module, avoids exposure to direct sunlight, high humidity, high or low

- Never leave LCD module in extreme condition (max./min storage/operate temperature) for more than 48hr.
- Recommend LCD module storage conditions is 0°C~40°C <80%RH.
- LCD module should be stored in the room without acid, alkali and harmful gas.
- Avoid dropping & violent shocking during transportation, and no excessive pressure press, moisture and sunlight.
- LCD module can be easily damaged by static electricity. Please maintain an optimum anti-static working environment to protect the LCD module. (eg. ground the soldering irons properly)
- Be sure to ground the body when handling LCD module.
- Only hold LCD module by its sides. Never hold LCD module by applying force on the heat seal or TAB.
- When soldering, control the temperature and duration avoid damaging the backlight guide or diffuser which might degrade the display result such as uneven display.
- Never let LCD module contact with corrosive liquids, which might cause damage to the backlight guide or the electric circuit of LCD module.
- Only clean LCD with a soft dry cloth, Isopropyl Alcohol or Ethyl Alcohol. Other solvents (e.g. water) may damage the LCD.
- Never add force to components of LCD module. It may cause invisible damage or degrade the module's reliability.
- When mounting LCD module, please make sure it is free from twisting, warping and bending.
- Do not add excessive force on surface of LCD, which may cause the display color change abnormally.
- LCD panel is made with glass. Any mechanical shock (e.g. dropping from high place) will damage the LCD module.
- Protective film is attached on LCD screen. Be careful when peeling off this protective film, since static electricity may be generated.
- The polarizer on LCD gets scratched easily. If possible, do not remove LCD protective film until the last step of installation.
- When peeling off protective film from LCD, static charge may cause abnormal display patterns. The symptom is normal, and it will turn back to normal in a short while.
- LCD panel has sharp edges, please handle with care.
- Never attempt to disassemble or rework LCD module.
- If display panel is damaged and liquid crystal substance leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes promptly wash it off using soap and water.






- Note:
- *1. LCD Display Type : TFT,Transmissive
 - *2. Pixel Arrangement : RGB-STRIPE
 - *3. Interface : MIPI
 - *4. Color Depth : 16.7M color
 - *5. Operating Voltage : 3.3V
 - *6. Backlight Supply : 60mA (Constant Current VF=9.0V typ.)
 - *7. Backlight : White LED
 - *8. Matched Connector: 62684-3211D0ALF Or Equivalent
 - *9. Operating Temperature : -20°C~70°C
 - *10. Storage Temperature : -30°C~80°C
 - *11. Unmarked Tolerance : ≤150,±0.3; >150,±0.5

K1 Terminal			
No	Pin Name	No	Pin Name
17	D2P	1	GND
18	GND	2	GND
19	D3N	3	ID(GND)
20	D3P	4	LEDK
21	GND	5	LEDA
22	IDVCC	6	NC
23	IDVCC	7	DDN
24	GND	8	DOP
25	VSP	9	GND
26	VSN	10	DIN
27	GND	11	DIP
28	CABC	12	GND
29	TE	13	CLKN
30	RESET	14	CLKP
31	GND	15	GND
32	GND	16	D2N

C		
B		
A		
RevNote		
Date		
LMT050FNCFWA outline Dwg		
Dwg No.	MK-008449-1-1	Date
Scale	1/1	Unit
mm	Paper Size	A3
Approved	Checked	Drawn
		Zhangwenbo

TOPWAY

Documents / Resources

	TOPWAY LMT050FNCFWA LCD Module Smart Displays [pdf] User Manual LMT050FNCFWA LCD Module Smart Displays, LMT050FNCFWA, LCD Module Smart Displays, Smart Displays, Displays
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References

- [-TFT](#)
- [-TFT](#)
- [User Manual](#)

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